

PATENT ASSIGNMENT

Electronic Version v1.1
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
CONVEYING PARTY DATA											
<table border="1" style="width: 100%; border-collapse: collapse;"> <thead> <tr> <th style="width: 70%;">Name</th> <th style="width: 30%;">Execution Date</th> </tr> </thead> <tbody> <tr> <td>Meng-Wei Chen</td> <td>08/09/2010</td> </tr> <tr> <td>Chi-Chuang Lee</td> <td>08/09/2010</td> </tr> <tr> <td>Chung-Hsien Lin</td> <td>08/09/2010</td> </tr> </tbody> </table>		Name	Execution Date	Meng-Wei Chen	08/09/2010	Chi-Chuang Lee	08/09/2010	Chung-Hsien Lin	08/09/2010		
Name	Execution Date										
Meng-Wei Chen	08/09/2010										
Chi-Chuang Lee	08/09/2010										
Chung-Hsien Lin	08/09/2010										
RECEIVING PARTY DATA											
<table border="1" style="width: 100%; border-collapse: collapse;"> <tr> <td style="width: 20%;">Name:</td> <td>Taiwan Semiconductor Manufacturing Company, Ltd.</td> </tr> <tr> <td>Street Address:</td> <td>No. 8, Li-Hsin Road 6</td> </tr> <tr> <td>City:</td> <td>Hsin-Chu</td> </tr> <tr> <td>State/Country:</td> <td>TAIWAN</td> </tr> <tr> <td>Postal Code:</td> <td>300-77</td> </tr> </table>		Name:	Taiwan Semiconductor Manufacturing Company, Ltd.	Street Address:	No. 8, Li-Hsin Road 6	City:	Hsin-Chu	State/Country:	TAIWAN	Postal Code:	300-77
Name:	Taiwan Semiconductor Manufacturing Company, Ltd.										
Street Address:	No. 8, Li-Hsin Road 6										
City:	Hsin-Chu										
State/Country:	TAIWAN										
Postal Code:	300-77										
PROPERTY NUMBERS Total: 1											
<table border="1" style="width: 100%; border-collapse: collapse;"> <thead> <tr> <th style="width: 30%;">Property Type</th> <th style="width: 70%;">Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>12854660</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	12854660						
Property Type	Number										
Application Number:	12854660										
CORRESPONDENCE DATA											
<p>Fax Number: (214)200-0853 <i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i></p> <p>Phone: 214-651-5000 Email: ipdocketing@haynesboone.com Correspondent Name: HAYNES AND BOONE, LLP Address Line 1: 2323 Victory Avenue Address Line 2: Suite 700 Address Line 4: Dallas, TEXAS 75219</p>											
ATTORNEY DOCKET NUMBER:	24061.1492										
NAME OF SUBMITTER:	Rachel L.I. Davis										

Total Attachments: 2
 source=1492_Assignment#page1.tif

501259719

PATENT
REEL: 024825 FRAME: 0271

OP \$40.00 12854660

ASSIGNMENT

WHEREAS, we,

- | | | | |
|-----|-----------------|----|---|
| (1) | Meng-Wei Chen | of | 9F-1, No. 198-2, Sec. 3, Huilai Road, Xitun District
Taichung City 407, Taiwan, R.O.C. |
| (2) | Chi-Chuang Lee | of | 8F, No. 70, Zhuangjing S. Road
Chubei City, Taiwan, R.O.C. |
| (3) | Chung-Hsien Lin | of | No. 17, Lane 8, Jinshan 6th Street, East District
Hsinchu City 300, Taiwan, R.O.C. |

have invented certain improvements in

OVERLAY MARK ENHANCEMENT FEATURE

for which we have executed an application for Letters Patent of the United States of America,

 X of even date filed herewith; and
 filed on Aug. 11, 2010 and assigned application number 12/854,660; and

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China, is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: Meng-Wei Chen

Residence Address: 9F-1, No. 198-2, Sec. 3, Huilai Road, Xitun District
Taichung City 407, Taiwan, R.O.C.

Dated: 8, 9, 2010

Meng-Wei Chen
Inventor Signature

Inventor Name: Chi-Chuang Lee

Residence Address: 8F, No. 70, Zhuangjing S. Road
Chubei City

Dated: 8, 9, 2010

Chi-Chuang Lee
Inventor Signature

Inventor Name: Chung-Hsien Lin

Residence Address: No. 17, Lane 8, Jinshan 6th Street, East District
Hsinchu City 300, Taiwan, R.O.C.

Dated: 8, 9, 2010

Chung-Hsien Lin
Inventor Signature